



DMS2220LFDB

### P-CHANNEL ENHANCEMENT MODE MOSFET WITH INTEGRATED SBR® SUPER BARRIER RECTIFIER

#### **Features**

- Low On-Resistance
  - 95mΩ @V<sub>GS</sub> = -4.5V
  - 120mΩ @V<sub>GS</sub> = -2.5V
  - 86mΩ (typ) @V<sub>GS</sub> = -1.8V
- Low Gate Threshold Voltage, -1.3V Max
- · Fast Switching Speed
- Low Input/Output Leakage
- Incorporates Low V<sub>F</sub> Super Barrier Rectifier (SBR)
- Low Profile, 0.5mm Max Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

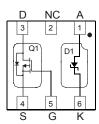
# **Mechanical Data**

- Case: U-DFN2020-6 Type B
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (approximate)

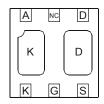
U-DFN2020-6 Type B



**Bottom View** 



Top View Internal Schematic



Bottom View Pin Configuration

## Ordering Information (Note 4)

Part Number	Case	Packaging
DMS2220LFDB-7	U-DFN2020-6 Type B	3000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



ME = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September) Dot denotes Pin 1

Date Code Key

Year	2008	2009	20	10	2011	2012	2013	2014	20	15	2016	2017
Code	V	W	Х	(	Υ	Z	Α	В	(	2	D	Е
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings – TOTAL DEVICE** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	1.4	W
Thermal Resistance, Junction to Ambient	R <sub>0JA</sub>	89	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Maximum Ratings – P-CHANNEL MOSFET – Q1 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	$V_{DSS}$	-20	V
Gate-Source Voltage	$V_{GSS}$	±12	V
Drain Current (Note 5)	ΙD	-3.5	Α
Pulsed Drain Current (Note 6)	I <sub>DM</sub>	-12	A

# **Maximum Ratings – SBR – D1** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	20	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	V
Average Rectified Output Current	I <sub>O</sub>	1	Α
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	3	А

# Electrical Characteristics – P-CHANNEL MOSFET – Q1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100 ±800	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.45	-	-1.3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
		_	60	95		$V_{GS} = -4.5V$ , $I_{D} = -2.8A$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	74	120	mΩ	$V_{GS} = -2.5V$ , $I_D = -2.0A$
		_	86	_		$V_{GS} = -1.8V, I_D = -1.0A$
Forward Transfer Admittance	Y <sub>fs</sub>	_	8	_	S	$V_{DS} = -5V, I_{D} = -2.8A$
Diode Forward Voltage (Note 7)	$V_{SD}$	_	0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1.6A$
DYNAMIC CHARACTERISTICS	DYNAMIC CHARACTERISTICS					
Input Capacitance	Ciss	_	632	_	pF	V 40V V 0V
Output Capacitance	Coss	_	65	_	pF	$V_{DS} = -10V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	54	_	pF	71 - 1.0101112

## Electrical Characteristics - SBR - D1 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

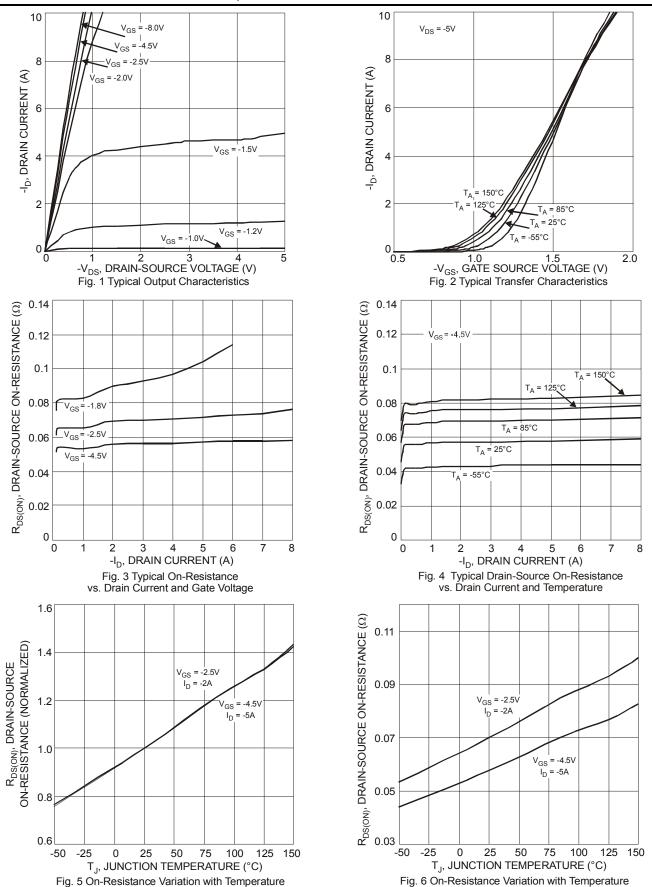
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	20	_	1	V	I <sub>R</sub> = 1mA
Forward Voltage	V <sub>F</sub>	1 1	1 1	0.45 0.52	V	I <sub>F</sub> = 0.5A I <sub>F</sub> = 1.0A
Reverse Current (Note 7)	I <sub>R</sub>	_	_	100	μΑ	V <sub>R</sub> = 20V

Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz Copper pad layout.

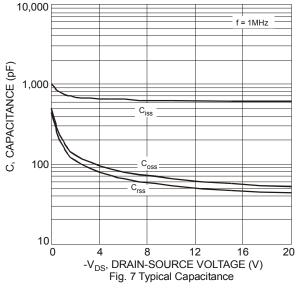
- 6. Repetitive rating, pulse width limited by junction temperature.
- 7. Short duration pulse test used to minimize self-heating effect.

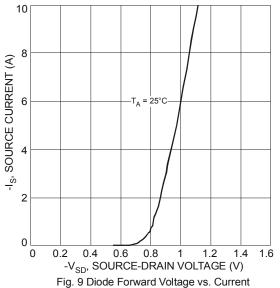


## **Q1 - P-CHANNEL MOSFET**









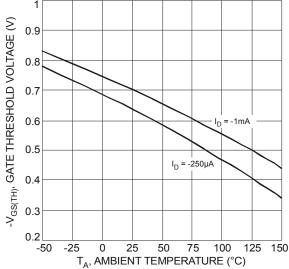


Fig. 8 Gate Threshold Variation vs. Ambient Temperature

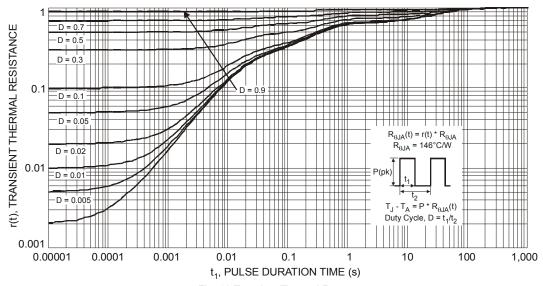
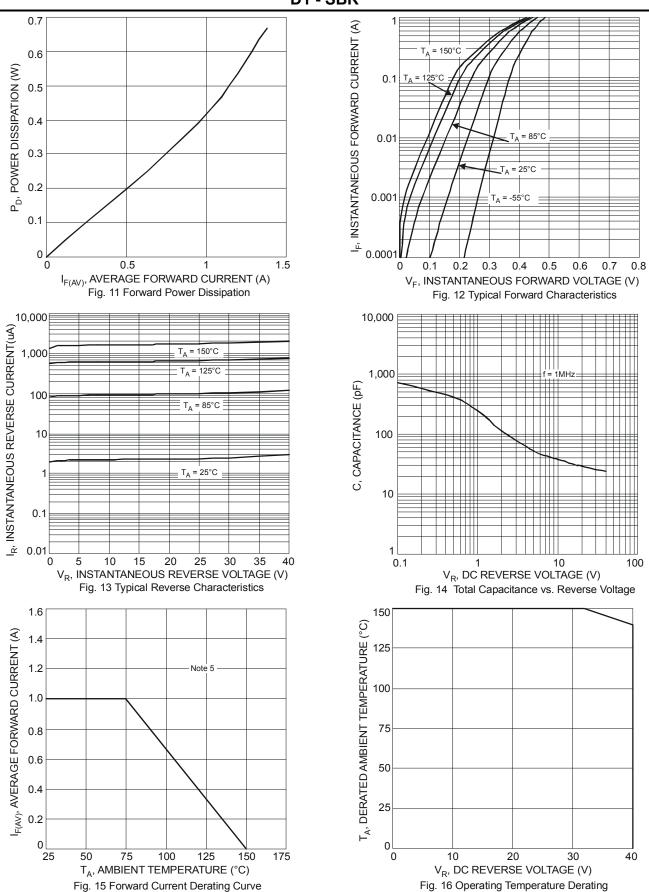


Fig. 10 Transient Thermal Response



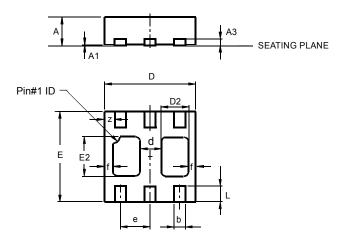
## D1 - SBR





# **Package Outline Dimensions**

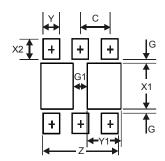
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN2020-6									
	Type B								
Dim	Min	Max	Тур						
Α	0.545	0.605	0.575						
A1	0	0.05	0.02						
A3			0.13						
b	0.20	0.30	0.25						
D	1.95	2.075	2.00						
d			0.45						
D2	0.50	0.70	0.60						
е			0.65						
E	1.95	2.075	2.00						
E2	0.90	1.10	1.00						
f			0.15						
L	0.25	0.35	0.30						
z	_	_	0.225						
All I	Dimens	ions in	mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65



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